

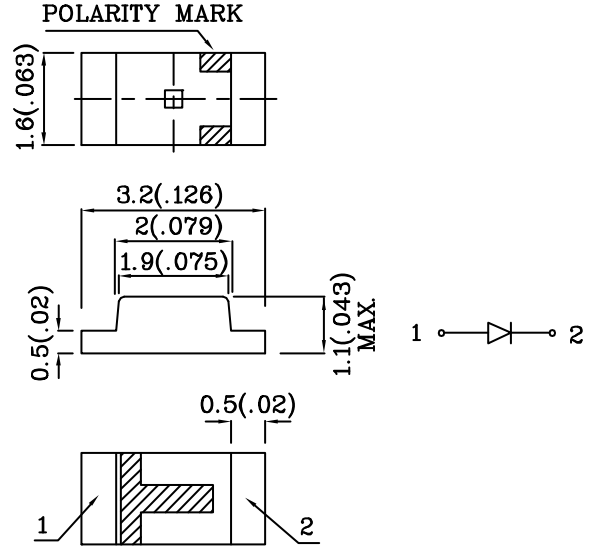
PRELIMINARY SPEC

Features

- 3.2mmx1.6mm SMT LED, 1.1mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



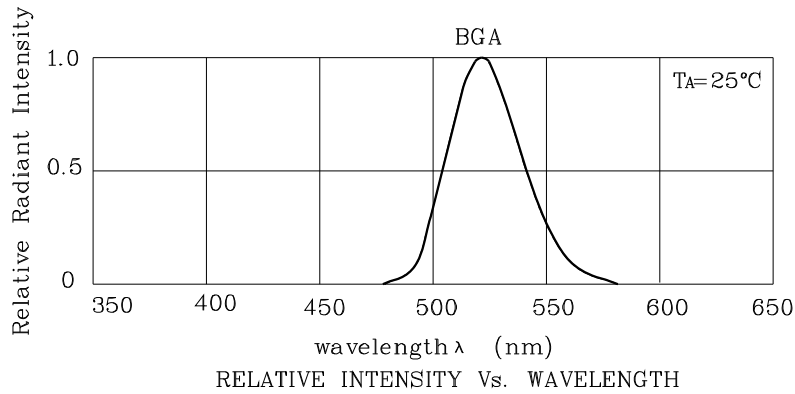
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ unless otherwise noted.
3. Specifications are subject to change without notice.

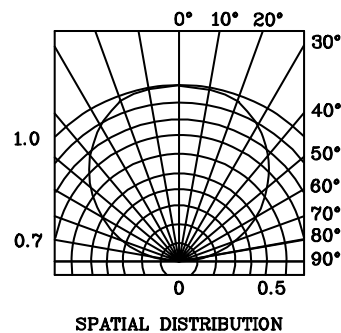
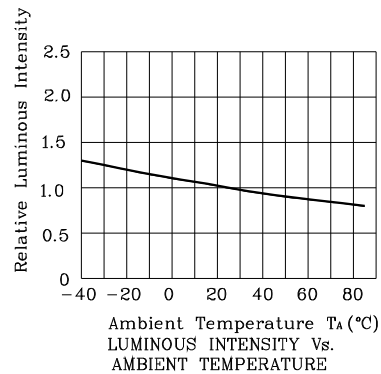
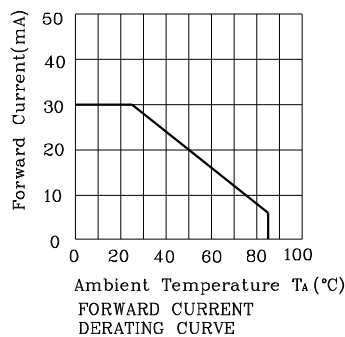
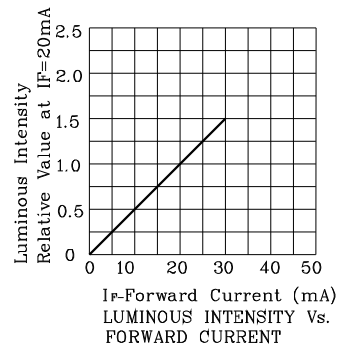
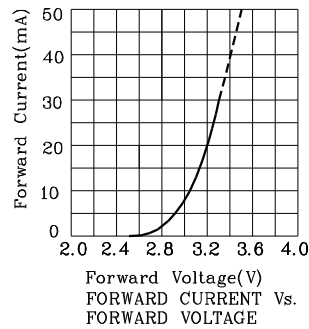
Absolute Maximum Ratings (TA=25°C)		BGA (InGaN)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	100	mA
Power Dissipation	P _T	120	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V

Operating Characteristics (TA=25°C)		BGA (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V _F	3.2	V
Forward Voltage (Max.) (I _F =20mA)	V _F	4.0	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λ _P	520	nm
Wavelength of Dominant Emission (Typ.) (I _F =20mA)	λ _D	525	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	100	pF

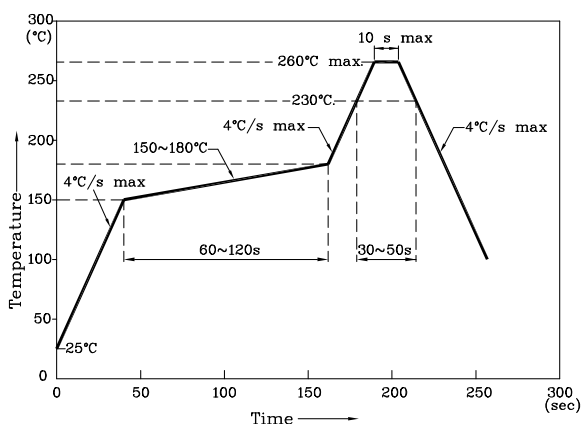
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λ _P	Viewing Angle 2 θ 1/2
				min.	typ.		
XZBGA55W	Green	InGaN	Water Clear	50	178	520	120°
Published Date : JAN 23 ,2008 Drawing No : XDSA8642 V3 Checked : B.L.LIU P.1/4							



❖ BGA



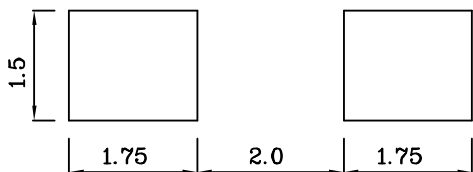
Reflow Soldering Profile For Lead-free SMT Process.



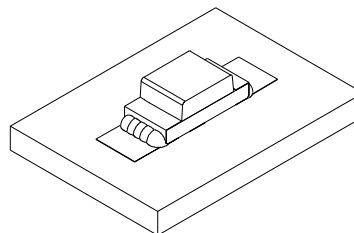
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

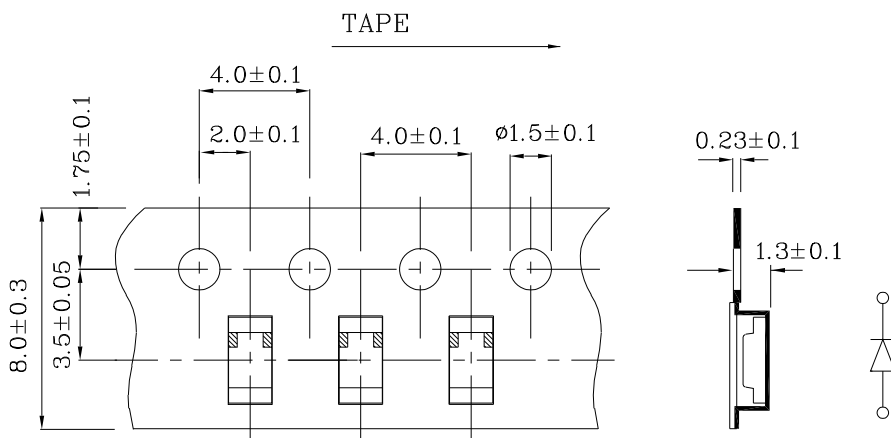
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

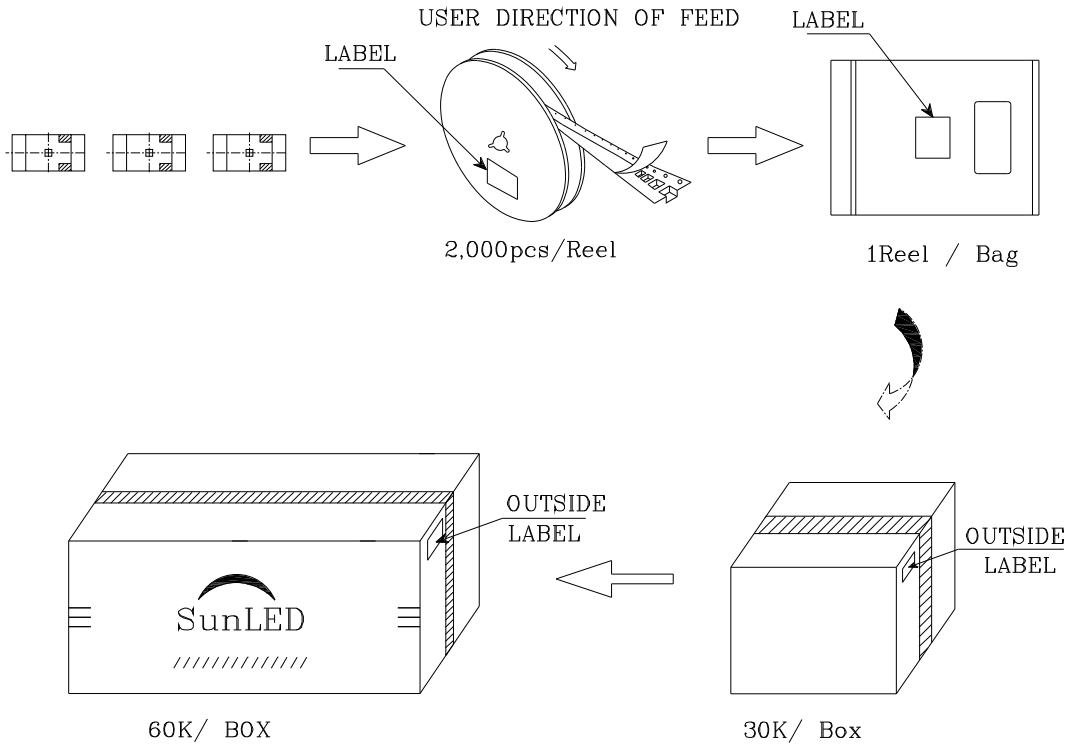

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

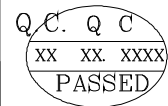

1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

XZBGA55W

	
P/NO : XZxxx55x	
QTY : 2,000 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	